

A METHOD AND STRUCTURE FOR IMPROVED ALIGNMENT TOLERANCE
IN MULTIPLE, SINGULARIZED PLUGS

Abstract of the Disclosure

- 5 An improved method and structure which increases the alignment tolerances
in multiple, singularized plugs are provided. The invention discloses a novel
method for forming individual plug contacts with increased surface area for
improved registration between semiconducting layers. Also the improved plug
contacts are particularly well suited to receiving contact formations which have any
10 taper to them. IGFETS and other devices formed from this design can be used in a
variety of beneficial applications, e.g. logic or memory.

"Express Mail" mailing label number: EL873859145US

Date of Deposit: December 4, 2001

This paper or fee is being deposited on the date indicated above with
the United States Postal Service pursuant to 37 CFR 1.10, and is
addressed to U.S. Patent and Trademark Office, Box Patent
Application, P.O. Box 2327, Arlington, VA 22202.